



アテナシス
(Athenasys Co., Ltd) の
ご紹介





会社紹介

<https://athenasys.co.jp/>

設立：2008年 10月 1日

事業内容：ライセンス販売（一部，サポート・コンサルティング）

取り扱っている製品

BOSPROM：プラズマシミュレーションで用いる輸送係数・反応レートの計算ツール（自社製品）

Lennard-Jones パラメータ 推算ツール（自社製品）

パートナー会社：Quantemol（英国） ※アテナシスは日本国内の代理店

Quantemol-VT (QVT)：HPEM を core としたプラズマシミュレーションソフトウェア

Quantemol-DB (QDB)：反応データベース，Global Model (QGM)

Quantemol-EC (QEC)：分子に対する電子衝突断面積の計算ツール

重点分野：

半導体製造装置のプラズマプロセス

その他，低温非平衡プラズマプロセス，電子衝突断面積を必要とする反応プロセス

主要なお客様：

半導体製造装置メーカー，デバイスメーカー

担当者はアネルバ（現キャノンアネルバ）で半導体製造装置の研究開発に長年従事



会社紹介 (2)

参加している学会, 委員会

応用物理学会 : 個人会員

DXプラズマプロセス委員会 : 企業会員

IOP (Institute of Physics) : 個人会員

化学工学会 : CVD反応分科会の個人会員

電気学会 : 液界面プラズマの実験・計算モデル標準化調査専門委員会

原子・分子衝突断面積および放電基礎データ査専門委員会

放電・プラズマ気相シミュレーション技法調査専門委員会

結晶成長学会 : 個人会員 (休眠中)

153委員会 : 終了後, DXプラズマプロセス委員会へ

参加している NPO

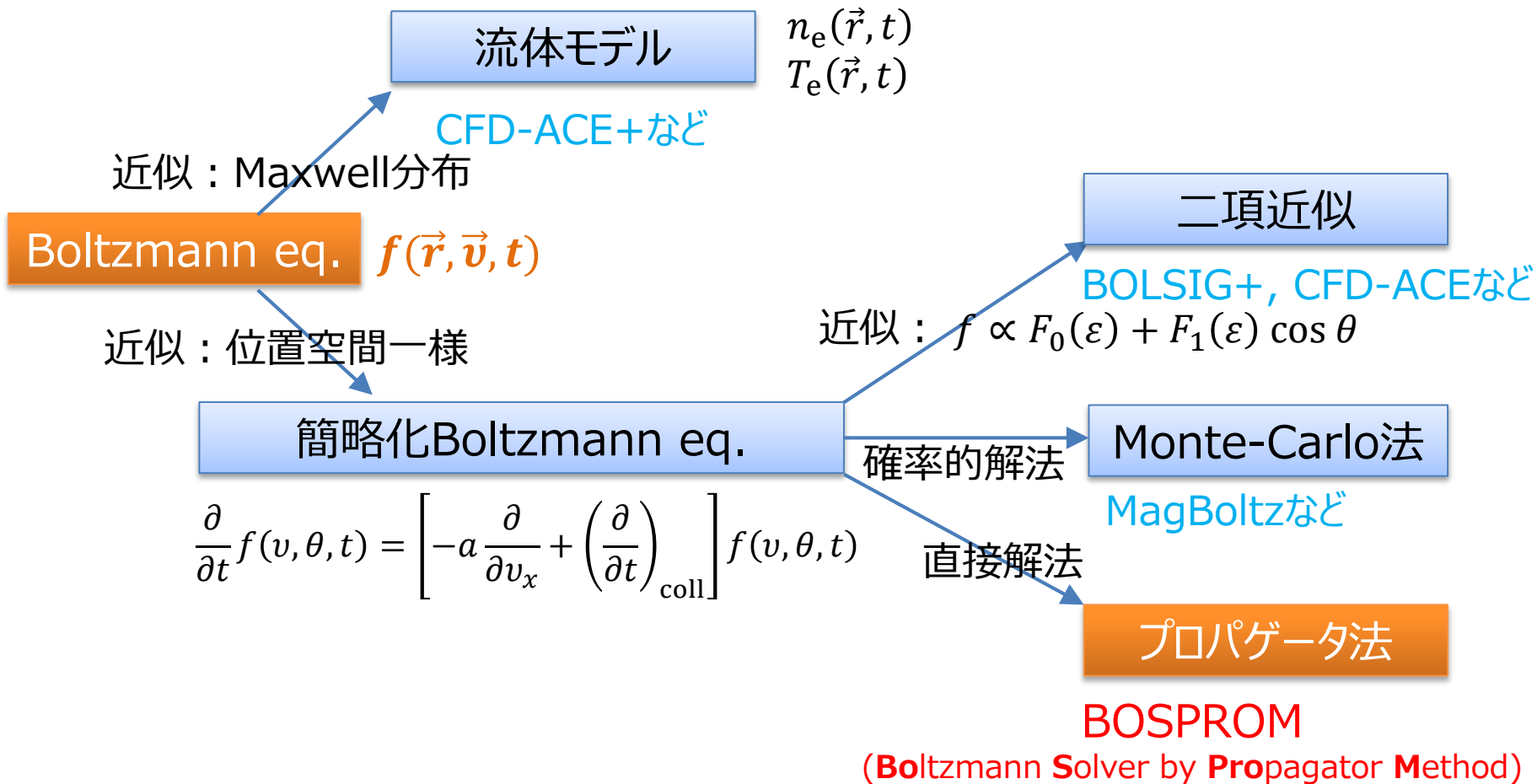
原子分子データ応用フォーラム



Swarm パラメータ, 反応レート の Lookup Table 作成ツール BOSPRM



プロパゲータ法 (分布関数 $f(\vec{v})$ 計算法の一種)



衝突断面積 → 分布関数 f → 反応レート定数, 輸送係数(移動度, 拡散係数)

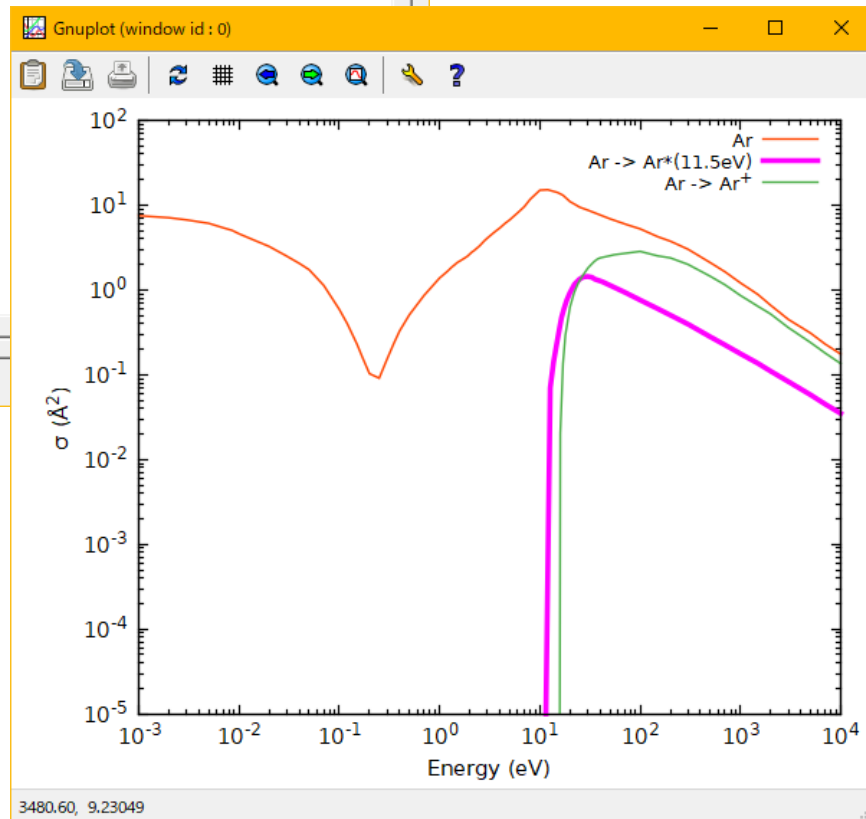
Swarm parameters



BOSPROM:衝突断面積データ選択・編集画面

The screenshot shows the BOSPROM software interface. The top menu includes File, Edit, Graph, Prefer, and Help. Below the menu is a toolbar with various icons. The main window is divided into two panes. The left pane, titled 'Library', lists various collision processes such as 'Ar -> Ar*(11.5eV)', 'CH4 -> CH3+H+', and 'CF4 -> CF4(V24)'. The right pane, titled 'Registered', shows a list of selected processes with their corresponding collision types and cross-section values. For example, '02 Ar -> Ar*(11.5eV)' is listed with 'EXCITATION' and a value of 11.3.

- 断面積データの編集が可能



The Dialog box is used for editing collision data. It contains a 'Name' field with 'Ar -> Ar*(12.9eV)', a 'Collision Type' dropdown menu set to 'EXCITATION', and a 'Threshold (eV) or Mass Ratio' field with '12.900'. Below these fields is a table with two columns: 'X Data' and 'Y Data'. The table contains 19 rows of data. To the right of the table are buttons for 'Delete', 'Insert Before', 'Append Last', 'OK', and 'Cancel'.

	X Data	Y Data
1	0.05	0
2	12.9	0
3	12.95	0.0495
4	13	0.08
5	13.05	0.0915
6	13.1	0.084
7	13.15	0.086
8	13.2	0.088
9	13.25	0.09
10	13.3	0.092
11	13.35	0.094
12	13.4	0.096
13	13.45	0.098
14	13.5	0.1
15	13.55	0.1015
16	13.6	0.103
17	13.65	0.1045
18	13.7	0.106
19	13.75	0.1075



BOSPROM: 計算条件設定画面・収束状況表示

bosprom : (D:/tukasa/home/bosprom/.workdir/)

File Edit Graph Prefer Help

σ Setup Results LUT

Project Name SF6_Ar_k Start Calc. N_{proc} 4

Append

Gas Composition

Gas	SF6	Ar	3	4	5	6	7	8	9	10	11	12	13	14	15
Ratio	0.8	0.2													

Pressure (Pa) 133.33 Temperature (K) 273.15

AC E/N (Td) 100 to 10 # 14 log sweep

Frequency (Hz) 13.56E6 E_{dd}/N (Td) 0

Converg. $\delta\epsilon$ (eV) 1E-10

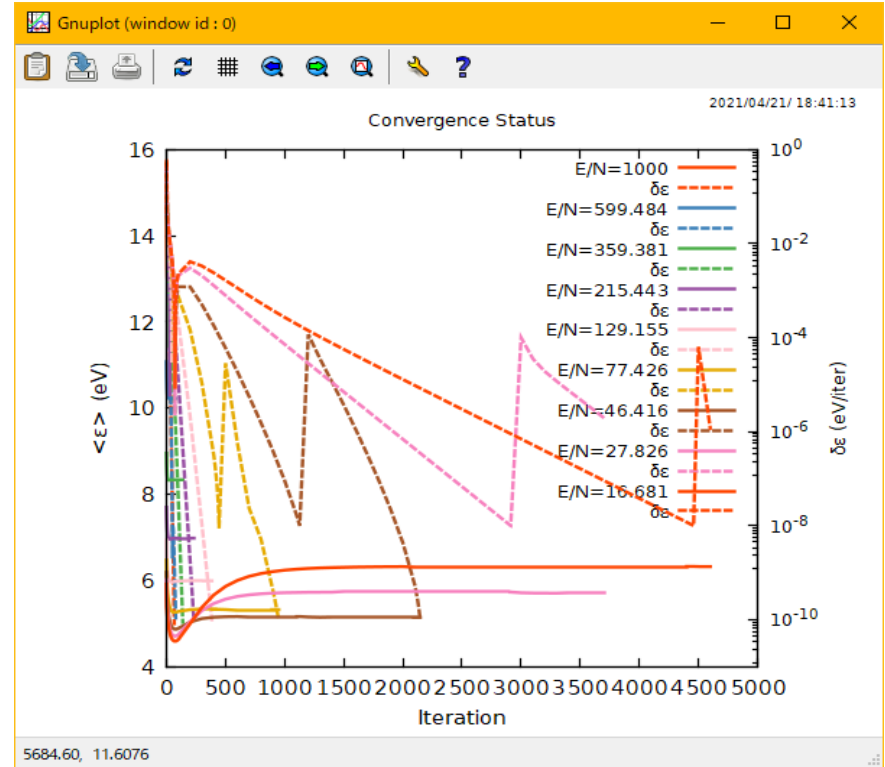
Optional Setting

Max. Energy (eV) 14 to 0.8 # 3 sweep

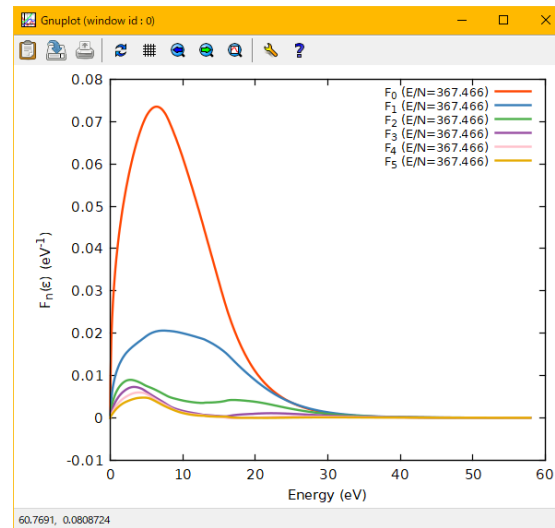
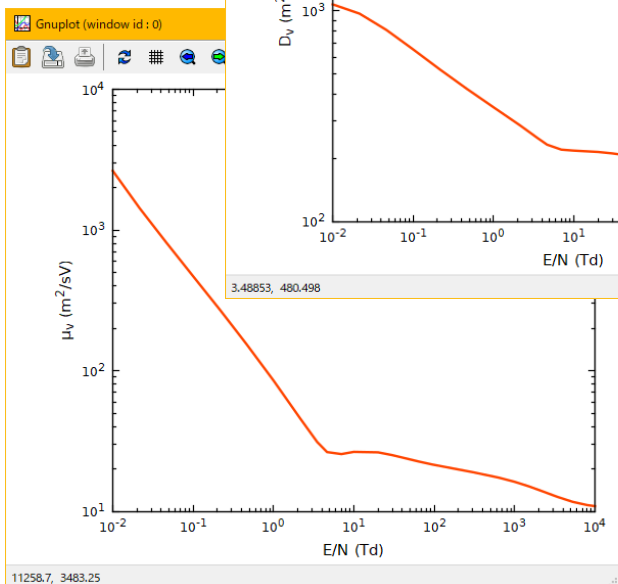
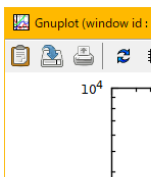
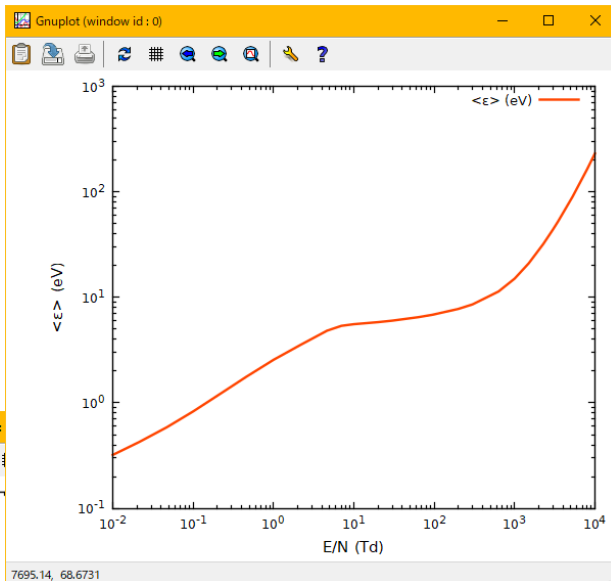
Energy Division N 14000 to 100000 # 3 sweep

$\Delta\epsilon$ (eV) 0.001

Angle Division N 90



BOSPROM : 結果表示画面



D:/tukasa/home/bosprom/Ar_hokudai_E-14_kkt.atp

File Edit Graph Prefer Help

σ | Setup Results LUT

Pickup Sort

Trend marker overlay

X axis: E/N (Td)

Y axis: $\langle \epsilon \rangle$ (eV)

cut copy paste

Data # : E/N 1: 0.01

Convergency overlay last

$\langle \epsilon \rangle$ (eV)

EEDF $F(\epsilon)$ Legendre

EEPF $F(\epsilon)/\sqrt{\epsilon}$

EVDF $f(v, \theta, 0)$ map polar log

AC phase: 0/4 π

	E/N(Td)	$\langle \epsilon \rangle$ (eV)	T_e (eV)	Ri(1/s)	R_{ϵ}
1	0.01	0.33896	0.22597	0	0
2	0.0164965	0.40454	0.2697	0	0
3	0.0272134	0.48643	0.32429	0	0
4	0.0448925	0.59605	0.39737	0	0
5	0.0740568	0.74196	0.49464	0	0
6	0.122168	0.93707	0.62471	0	0
7	0.201534	1.1972	0.79816	0	0
8	0.33246	1.5575	1.0383	2.135e-237	0
9	0.548442	1.9523	1.3016	8.6792e-212	0
10	0.904736	2.4667	1.6444	6.1143e-100	0
11	1.4925	3.063	2.042	3.1205e-046	0
12	2.46209	3.749	2.4993	5.0678e-021	0
13	4.06159	4.6062	3.0708	5.2704e-009	0
14	6.70019	5.3355	3.557	0.0045901	0
15	11.053	5.6064	3.7376	10.103	0
16	18.2335	5.7872	3.8581	988.27	0
17	30.0788	6.0134	4.0089	23160	0
18	49.6195	6.3154	4.2103	2.3305e+005	0
19	81.8547	6.7051	4.4701	1.4411e+006	0
20	135.031	7.2187	4.8125	6.6435e+006	0



BOSPROM: プラズマ計算用 lookup-table 作成画面

The screenshot shows the BOSPROM software interface. The main panel is divided into tabs: σ , Setup, Results, and LUT. The LUT tab is selected, showing a table of data and configuration options.

Configuration options on the left:

- Update: $D=\mu T_e$
- Number of data: 120
- Pressure (Pa): 13.333
- k order: 4 2 3 1
- T_e range: 2 to 50
- N_e (m^{-3}): 1E+13
- Y-axis: k1 (m^3/s)
- marker overlay
- Export (CFD-ACE+): Te - k, μ , D Te - k
- R_name: Argon_hokudai
- Import: CFD-ACE+
- Equally spaced

Table of data (Te (eV), k1 (m^3/s), k2 (m^3/s), k3 (m^3/s)):

Te (eV)	k1 (m^3/s)	k2 (m^3/s)	k3 (m^3/s)
2	0	2.47996e-24	2.65474e-25
2.40336	0	6.79372e-24	7.27252e-25
2.80672	1.83832e-27	7.63325e-20	1.23452e-19
3.21008	3.84433e-27	1.5962e-19	2.58164e-19
3.61345	2.94471e-21	1.56789e-18	4.68609e-18
4.01681	3.5004e-18	3.0896e-17	4.74729e-17
4.42017	7.78969e-17	2.08562e-16	1.72251e-16
4.82353	4.07528e-16	5.53056e-16	3.85831e-16
5.22689	1.05326e-15	9.51372e-16	6.73392e-16
5.63025	1.96409e-15	1.36599e-15	1.01721e-15
6.03361	2.94441e-15	1.76166e-15	1.36413e-15
6.43697	4.30907e-15	2.05253e-15	1.7282e-15
6.84034	5.67374e-15	2.3434e-15	2.09227e-15
7.2437	7.0384e-15	2.63427e-15	2.45634e-15
7.64706	8.40306e-15	2.92514e-15	2.82042e-15
8.05042	9.77468e-15	3.19317e-15	3.16977e-15
8.45378	1.11806e-14	3.34845e-15	3.44651e-15
8.85714	1.25865e-14	3.50372e-15	3.72325e-15
9.2605	1.39924e-14	3.659e-15	3.99999e-15
9.66387	1.53983e-14	3.81428e-15	4.27673e-15

- 計算結果から T_e ベースの LUT (lookup-table) を作成
- CFD-ACE+ や COMSOL に import する format で出力が可能




Lennard-Jones パラメータ推算ツール



分子の加算因子・沸点から Lennard-Jones パラメータを推算

熱流体・プラズマのシミュレーションで必要となる L-J parameters を推算

Lyndersenの臨界定数の加算因子		Lyndersenの臨界定数の加算因子		Lyndersenの臨界定数の加算因子		Lyndersenの方法	
	個数		個数		個数		
非環状加算因子		ハロゲン加算因子		窒素加算因子		標準沸点Tb(K):	390.65 (Input)
-CH3	1	-F	5	-NH2	0	分子量 (M) :	182.10 (Input)
-CH2-	0	-Cl	0	>NH	0	偏心因子 ω	0.51
>CH-	0	-Br	0	>NH(R)	0	Tc	548.65
>C<	0	-I	0	>N-	0	Pc	26.71
=CH2	0	酸素加算因子		>N-(R)	0	Vc	401.00
=CH-	0	-OH(Alcohol)	0	-CN	0	Lennard-Jones	
=C<	0	-OH(Phenol)	0	-NO2	0	σ	6.33
=C=	0	-O-	0	イオウ加算因子		ϵ/k	481.79 (K)
#CH	0	-O-(R)	0	-SH	0		
#C-	0	>C=O	0	-S-	0		
環状加算因子		>C=O(R)	0	-S-(R)	0		
-CH2-(R)	0	O=HC-(Aldehyde)	0	=S	0		
>CH-(R)	0	-COOH(Acid)	0	その他	0		
>C<(R)	0	-COO-(Ester)	0	>Si<	0		
=CH-(R)	6	=O	0	>B-	0		
=C<(R)	0						
=C=(R)	0						



プラズマシミュレーション
ソフトウェア
QVT (HPEM)



REVIEW ARTICLE

※ HPEM に GUI を追加したものが Q-VT

Hybrid modelling of low temperature plasmas for fundamental investigations and equipment design

Mark J Kushner

Electrical Engineering and Computer Science Department, University of Michigan, 1301 Beal Ave., Ann Arbor, MI 48109-2122, USA

E-mail: mjkush@umich.edu

Received 12 May 2009, in final form 12 June 2009

Published 18 September 2009

Online at stacks.iop.org/JPhysD/42/194013

Abstract

The modelling of low temperature plasmas for fundamental investigations and equipment design is challenged by conflicting goals—having detailed, specialized algorithms which address sometimes subtle physical phenomena while also being flexible enough to address a wide range of process conditions. Hybrid modelling (HM) is a technique which provides many opportunities to address both fundamental physics and practical matters of equipment design. HM is a hierarchical approach in which modules addressing different physical processes on vastly disparate timescales are iteratively combined using time-slicing techniques. By compartmentalizing the physics in each module to accept given inputs and produce required outputs, different algorithms can be used to represent the same physical processes. In this manner, the algorithms best suited for the conditions of interest can be used without affecting other modules. In this paper, the basis and implementation of HM are discussed using examples from simulations of inductively coupled plasmas.

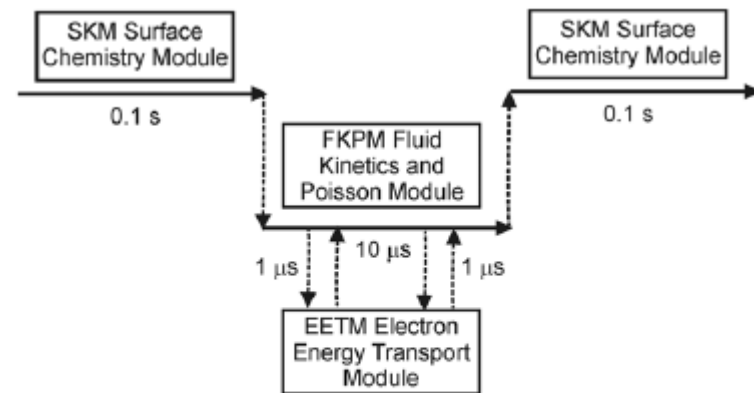


Figure 4. Schematic of time slicing between modules where the final outcome is a SS solution. Sub-time slicing may occur between the FKPM and EETM as those modules are more tightly coupled.



HPEM の計算例

※ ミシガン大と Samsung の共著

Voltage waveform tailoring for high aspect ratio plasma etching of SiO₂ using Ar/CF₄/O₂ mixtures: Consequences of ion and electron distributions on etch profiles EP

Cite as: J. Vac. Sci. Technol. A 41, 013006 (2023); doi: 10.1116/6.0002290
Submitted: 14 October 2022 · Accepted: 13 December 2022 ·
Published Online: 30 December 2022



Florian Krüger,^{1,a)} Hyunjae Lee,^{2,b)} Sang Ki Nam,^{2,c)} and Mark J. Kushner^{1,d)}

AFFILIATIONS

¹Electrical Engineering and Computer Science Department, University of Michigan, 1301 Beal Ave., Ann Arbor, Michigan 48109-2122

²Mechatronics R&D Center, Samsung Electronics Co., Ltd., 1-1 Samsungjeonja-ro, Hwaseong-si, Gyeonggi-do 18448, South Korea

^{a)}Electronic mail: fkrueger@umich.edu

^{b)}Electronic mail: hj0928.lee@samsung.com

^{c)}Electronic mail: sangki.j.nam@samsung.com

^{d)}Author to whom correspondence should be addressed: mjkush@umich.edu

ABSTRACT

The quality of high aspect ratio (HAR) features etched into dielectrics for microelectronics fabrication using halogen containing low temperature plasmas strongly depends on the energy and angular distribution of the incident ions (IEAD) onto the wafer, as well as potentially that of the electrons (EEAD). Positive ions, accelerated to high energies by the sheath electric field, have narrow angular spreads and can penetrate deeply into HAR features. Electrons typically arrive at the wafer with nearly thermal energy and isotropic angular distributions and so do not directly penetrate deeply into features. These differences can lead to positive charging of the insides of the features that can slow etching rates and produce geometric defects such as twisting. In this work, we computationally investigated the plasma etching of HAR features into SiO₂ using tailored voltage waveforms in a geometrically asymmetric capacitively coupled plasma sustained in an Ar/CF₄/O₂ mixture at 40 mTorr. The tailored waveform consisted of a sinusoidal wave and its higher harmonics with a fundamental frequency of 1 MHz. We found that some degree of control of the IEADs and EEADs is possible by adjusting the phase of higher harmonics φ through the resulting generation of electrical asymmetry and electric field reversal. However, the IEADs and EEADs cannot easily be separately controlled. The control of IEADs and EEADs is inherently linked. The highest quality feature was obtained with a phase angle $\varphi = 0^\circ$ as this value generated the largest (most negative) DC self-bias and largest electric field reversal for accelerating electrons into the feature. That said, the consequences of voltage waveform tailoring (VWT) on etched features are dominated by the change in the IEADs. Although VWT does produce EEADs with higher energy and narrower angular spread, the effect of these electrons on the feature compared to thermal electrons is not large. This smaller impact of VWT produced EEADs is attributed to thermal electrons being accelerated into the feature by electric fields produced by the positive in-feature charging.

Published under an exclusive license by the AVS. <https://doi.org/10.1116/6.0002290>

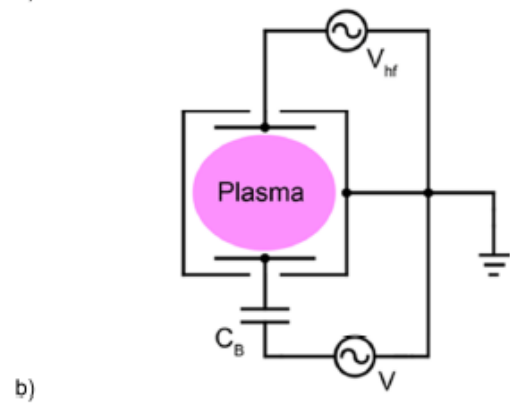
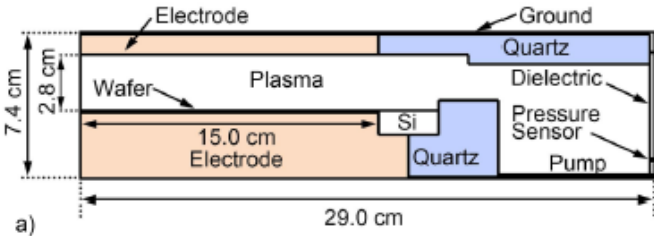






FIG. 1. Schematics of the reactor. (a) The two frequency CCP has the VWT power applied to the lower electrode and a sinusoidal, 80 MHz waveform applied to the top. (b) Electrical schematic of the system. Reproduced with permission from Krüger *et al.*, Plasma Sources Sci. Technol. 30, 085002 (2021). Copyright 2021 IOP Publishing Ltd.



反応モデルのデータベース QDB

The 2021 release of the Quantemol database (QDB) of plasma chemistries and reactions

Jonathan Tennyson^{1,*}, Sebastian Mohr², M Hanicinec¹, Anna Dzarasova², Carrick Smith², Sarah Waddington², Bingqing Liu¹, Luís L Alves³, Klaus Bartschat⁴, Annemie Bogaerts⁵, Sebastian U Engelmann⁶, Timo Gans^{7,13}, Andrew R Gibson^{8,9}, Satoshi Hamaguchi¹⁰, Kathryn R Hamilton⁴, Christian Hill¹¹, Deborah O'Connell^{7,13}, Shahid Rauf¹², Kevin van 't Veer⁵ and Oleg Zatsarinny^{4,f}

¹ Department of Physics and Astronomy, University College, London, Gower St., London WC1E 6BT, United Kingdom

² Quantemol Ltd., 320 City Rd, London EC1V 2NZ, United Kingdom

³ Instituto de Plasmas e Fusão Nuclear, Instituto Superior Técnico, Universidade de Lisboa, Av Rovisco Pais 1049-001 Lisboa, Portugal

⁴ Department of Physics and Astronomy, Drake University, IA 50311, United States of America

⁵ Research group PLASMANT, University of Antwerp, Belgium

⁶ IBM T J Watson Research Center, Yorktown Heights, NY 10598, United States of America

⁷ National Centre for Plasma Science Technology, Dublin City University, Dublin, Ireland

⁸ Research Group for Biomedical Plasma Technology, Ruhr-Universität Bochum, Germany

⁹ Institute of Electrical Engineering and Plasma Technology, Ruhr-Universität Bochum, Germany

¹⁰ Center for Atomic and Molecular Technologies, Graduate School of Engineering, [Osaka University](#), Japan

¹¹ Atomic and Molecular Data Unit, Division of Physical and Chemical Sciences, International Atomic Energy Agency, Vienna, Austria

¹² [Applied Materials Inc.](#), Sunnyvale, CA 94085, United States of America

¹³ School of Physical Sciences, Faculty of Science and Health, Dublin City University, Dublin, Ireland

Abstract

The Quantemol database (QDB) provides cross sections and rates of processes important for plasma models; heavy particle collisions (chemical reactions) and electron collision processes are considered. The current version of QDB has data on 28 917 processes between 2485 distinct species plus data for surface processes. These data are available via a web interface or can be delivered directly to plasma models using an application program interface; data are available in formats suitable for direct input into a variety of popular plasma modeling codes including HPEM, COMSOL, ChemKIN, CFD-ACE+, and VisGlow. QDB provides ready assembled plasma chemistries plus the ability to build bespoke chemistries. The database also provides a Boltzmann solver for electron dynamics and a zero-dimensional model. These developments, use cases involving O₂, Ar/NF₃, Ar/NF₃/O₂, and He/H₂O/O₂ chemistries, and plans for the future are presented.

Keywords: atomic and molecular data, chemistries, plasma models, low temperature plasmas

Q-VT(HPEM), COMSOL, CHEMKIN, CFD-ACE+, VizGlow 等の商用コードに import 可能



Rate Coefficient Calculator

The Quantemol team has developed a machine learning regression model to rapidly estimate reaction rate coefficients for heavy particle collisions. The model was trained on approximately 10,000 instances of kinetic data obtained from four popular plasma process databases: QDB [1], NFRI [2], KIDA [3], and UDfA [4]. The model features were engineered from commonly available data that describe individual chemical species involved in the reactions, such as molar masses, charges, enthalpies of formation, dipole moments, polarizabilities, and elemental composition data.

The final prediction algorithm is a voting regressor that combines distinct, optimised machine learning regressors, including support vector regressor [5], random forest regressor [6], gradient-boosted trees regressor [6, 7], and k-nearest neighbours regressor [8].

An evaluation of the prediction algorithm was performed on a dataset containing over 1000 test reactions. It was discovered that, for more than 87% of these reactions, the predicted rate coefficient values had an error of less than one order of magnitude. Please note, the prediction error for certain reactions was significantly higher.

We invite all users to benefit from this model and populate your chemistry sets with missing data for heavy particle reactions.

However, it is important to keep in mind that while machine learning models can offer fast predictions, they may not be as accurate as more complex calculations like quantum chemistry methods. Therefore, the results obtained with machine learning models should be treated with a certain degree of scepticism.

Please enter the chemical reaction that you wish to investigate. Please note:

- Elements are case-sensitive, e.g. Ar,O,CH₄,HCl
- Ions are specified by + or -, eventually followed by the charge number, e.g. H⁺, Cl⁻, Ar⁺²
- Species are separated by ' + ' and reactants and products are separated by ' -> '. Please mind the spaces between the species and these symbols.
- Reaction rate coefficient only works for two reactant-product pairs e.g. 'Ar⁺ + H₂O -> Ar + H₂O⁺' or for reactions with three products e.g. 'O₃ + HO₂ -> O₂ + O₂ + OH'

Reaction:

SUBMIT

RESET



Fast species ranking for iterative species-oriented skeletal reduction of chemistry sets

Martin Hanicinec¹, Sebastian Mohr² and Jonathan Tennyson^{1,*}

¹ Department of Physics and Astronomy, University College, London, Gower St., London, WC1E 6BT, United Kingdom

² Quantemol Ltd, 320 City Road, London, EC1V 2NZ, United Kingdom

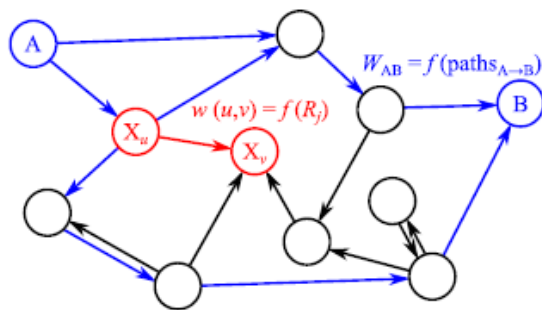


Figure 3. Depiction of a *chemistry graph* with nodes representing species and directional edges representing asymmetric direct interactions between species, weighted by the direct interaction coefficients. A direct interaction coefficient $w(u, v)$ between u th and v th species is depicted in red, while the asymmetric coupling coefficient W_{AB} between species A and B is hinted in blue, depending on all the paths $p(A \rightarrow B)$ in the chemistry graph leading from A to B.

Abstract

A fast algorithm is developed for ranking the species in a chemistry set according to their importance to the modeled densities of user-specified species of interest. The species ranking can be constructed for any set of user-specified plasma conditions, but here we focus predominantly on low-temperature plasmas, with gas temperatures between 300 and 1500 K covering the typical range of ICP and CCP plasma sources. This ranking scheme can be used to acquire insight into complex chemistry sets for modeling plasma phenomena or for a species-oriented reduction of the given chemistry set. The species-ranking method presented is based on a graph-theoretical representation of the detailed chemistry set and establishing indirect asymmetric coupling coefficients between pairs of species by the means of widely used graph search algorithms. Several alternative species-ranking schemes are proposed, all building on the theory behind different flavors of the directed relation graph method. The best-performing ranking method is identified statistically, by performing and evaluating a species-oriented iterative skeletal reduction on six, previously available, test chemistry sets (including O_2 -He and N_2 - H_2) with varying plasma conditions. The species-ranking method presented leads to reductions of between 10 and 75% in the number of species compared to the original detailed chemistry set, depending on the specific test chemistry set and plasma conditions.

Keywords: plasma modeling, chemistry reduction, species ranking, chemistry graph



Quantemol Global model (QGM)

Ar/O2/C4F6/C4F8 mixture の例

Set Generation Chemistry Set Boltzmann Solver Model Settings Results Analysis

85 species are selected. **85 species**

		Name	Sticking Coefficient	Return Coefficient	Ret
<input checked="" type="checkbox"/>	Properties	Ar	0.0000	0.0000	Ar
<input checked="" type="checkbox"/>	Properties	Ar+	1.0000	1.0000	Ar
<input checked="" type="checkbox"/>	Properties	Ar2+	1.0000	2.0000	Ar
<input checked="" type="checkbox"/>	Properties	Ar3+	1.0000	3.0000	Ar
<input checked="" type="checkbox"/>	Properties	Ar[**]	1.0000	1.0000	Ar
<input checked="" type="checkbox"/>	Properties	Ar[*]	1.0000	1.0000	Ar
<input checked="" type="checkbox"/>	Properties	Ar[3*]	1.0000	1.0000	Ar
<input checked="" type="checkbox"/>	Properties	C	0.0000	0.0000	C

Auto-Add Reactions

Add Custom Species

Add QDB Species

Filtering

Filtering

- Show only selected species
- Ground State Neutrals
- Excited States
- Positive Ions
- Negative Ions

Excited States

- Use pooled states
- Use distinct states

885 reactions are selected. **885 reactions**

		Reaction	A	n	E	Thresh
<input checked="" type="checkbox"/>	Info	O + O- > e- + O2	2.30e-10	0.00	0.00	0.00
<input checked="" type="checkbox"/>	Info	e- + O2 > O + O-	1.39e-09	-1.37	6.77	0.00
<input checked="" type="checkbox"/>	Info	e- + C2F5 > CF3- + CF2	5.34e-09	-1.44	3.8	0.00
<input checked="" type="checkbox"/>	Info	Ar + Ar+ > Ar + Ar+	5.66e-10	0.50	0.00	0.00
<input checked="" type="checkbox"/>	Info	e- + Ar2+ > Ar + Ar[*]	2.20e-05	-0.64	0.00	0.00
<input checked="" type="checkbox"/>	Info	e- + Ar > e- + Ar	3.67e-07	-0.11	3.49	0.00

Backward

Forward

Auto-Update Species

Show only selected reactions

Add Reaction

Filter by Type

show electron collisions

show heavy particle collisions

Filter by Reactants

Has Reactants

Ar
Ar+
Ar2+
Ar3+
Ar[**]
Ar[*]
Ar[3*]
C
C+
C-
C2

Filter by Products

Has Products

Ar
Ar+
Ar2+
Ar3+
Ar[**]
Ar[*]
Ar[3*]
C
C+
C-
C2

Enable Consistency Checks

Consistency Checks

Some Ion-Ion Recombination reactions are missing!

Show

Some symmetric charge exchange reactions are missing!

Show

The following species are not produced by any gas phase reactions

C4F6 : Produced only at surfaces

The following species are not consumed by any gas phase reactions:

C2F2 : No loss channels in gas phase or at surfaces C3F4 : No loss channels in gas phase or at surfaces C3F+ : Consumed only at surfaces C3F2+ : Consumed only at surfaces C3F3+ : Consumed only at surfaces
 C3F4+ : Consumed only at surfaces C4F4+ : Consumed only at surfaces C4F5+ : Consumed only at surfaces C4F6+ : Consumed only at surfaces C4F7+ : Consumed only at surfaces
 CF3[v=*] : Consumed only at surfaces



QGM (cont.) reduced model (※AMAT の検討例)

Ar/NF₃/O₂ and Ar/NF₃ plasmas



概要 :

主要な species と反応式を抽出し, Species の数を 2/3 程度, 反応式を 1/3 程度に低減して, ほぼ同等の結果を得ることに成功

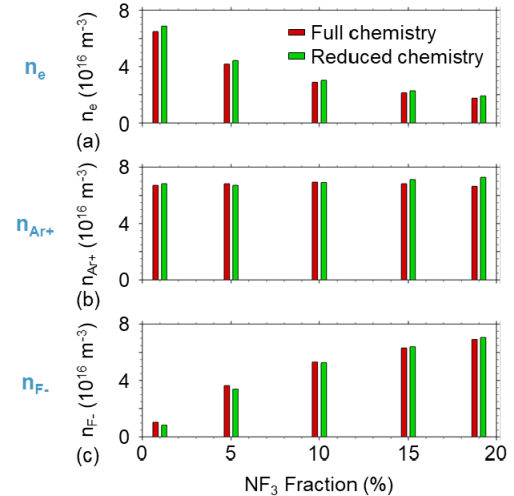
Modeling of Inductively Coupled Ar/NF₃/O₂ and Ar/NF₃ Plasmas

Shahid Rauf
Applied Materials, Inc., Santa Clara, CA, USA

2023 Quantemol Workshop
London, England
April 14, 2023

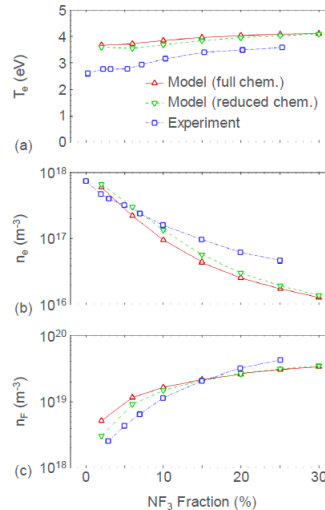
Spatially-Averaged Charged Species Densities

- The full and reduced chemistries capture the trends in charged species vs. NF₃ / O₂ fraction in the gas mixture. Densities are also quantitatively close.
- n_e decreases with increasing NF₃ fraction in the gas mixture due to the high electronegativity of NF₃.
- Density of the dominant negative ion, F⁻, increases with increasing NF₃ fraction in the gas mixture.



Model Validation in Ar/NF₃

- The computed n_e and T_e at $(r, z) = (0, 4.5)$ cm are compared to measurements in Ar/NF₃ plasma.
- In addition, spatially-averaged F density is compared to actinometry-based measured density.
- F recombination coefficient ($\text{F} \rightarrow \text{F}_2$ on surfaces) was adjusted (0.004) based on experimental validation.
- The model captures the experimental trends in these quantities:
 - ▶ n_e decreases with increasing NF₃ fraction due to enhanced electronegativity
 - ▶ F density increases with NF₃ fraction due to more F availability
- Plasma chemistry mechanism has too many “degrees of freedom” to attempt a better match.



▪ 140 W, 30 mTorr, Ar/NF₃/O₂ = 80/x/20-x



▪ 140 W, 30 mTorr, Ar/NF₃ = 100-x/x










電子衝突断面積の推算ツール QEC



Article

Quantemol Electron Collisions (QEC): An Enhanced Expert System for Performing Electron Molecule Collision Calculations Using the R-Matrix Method

Bridgette Cooper¹, Maria Tudorovskaya², Sebastian Mohr², Aran O'Hare¹, Martin Hanicinec¹, Anna Dzarasova², Jimena D. Gorfinkiel³, Jakub Benda³, Zdeněk Mašín⁴, Ahmed F. Al-Refai¹, Peter J. Knowles⁵ and Jonathan Tennyson^{1,*}

¹ Department of Physics and Astronomy, University College London, London WC1E 6BT, UK; bridgette.cooper@ucl.ac.uk (B.C.); aran.ohare@ucl.ac.uk (A.O.); hanicinecm@gmail.com (M.H.); ahmed.al-refaie.12@ucl.ac.uk (A.F.A.-R.)

² Quantemol Ltd., 320 City Rd, The Angel, London EC1V 2NZ, UK; mtudorov@quantemol.com (M.T.); s.mohr@quantemol.com (S.M.); adzarasova@quantemol.com (A.D.)

³ School of Physical Sciences, The Open University, Walton Hall, jimena.gorfinkiel@open.ac.uk (J.D.G.); jakub.benda@open.ac.uk

⁴ Institute of Theoretical Physics, Faculty of Mathematics and Physics, 180 00 Prague 8, Czech Republic; zde84nk@gmail.com

⁵ School of Chemistry, Cardiff University, Main Building, Park Pl knowlespj@cardiff.ac.uk

* Correspondence: j.tennyson@ucl.ac.uk

Abstract: Collisions of low energy electrons with molecules are important for understanding many aspects of the environment and technologies. Understanding the processes that occur in these types of collisions can give insights into plasma etching processes, edge effects in fusion plasmas, radiation damage to biological tissues and more. A radical update of the previous expert system for computing observables relevant to these processes, Quantemol-N, is presented. The new Quantemol Electron Collision (QEC) expert system simplifies the user experience, improving reliability and implements new features. The QEC graphical user interface (GUI) interfaces the Molpro quantum chemistry package for molecular target setups, and the sophisticated UKRmol+ codes to generate accurate and reliable cross-sections. These include elastic cross-sections, super elastic cross-sections between excited states, electron impact dissociation, scattering reaction rates, dissociative electron attachment, differential cross-sections, momentum transfer cross-sections, ionization cross sections, and high energy electron scattering cross-sections. With this new interface we will be implementing dissociative recombination estimations, vibrational excitations for neutrals and ions, and effective core potentials in the near future.

Keywords: cross sections; elastic scattering; inelastic scattering; electronic excitation; rotational excitation; electron scattering; ionization; momentum transfer



QEC (続き)

Underlying Codes : UK-RMOL+

What does Quantemol-EC do?

Calculates a variety of observables for electron molecule collisions including:

Zero – high electron energy extension for all cross sections*

- Elastic cross-sections
- Electronic excitation cross-sections
- Super-elastic/Quenching cross-sections
- Electron impact dissociation
- Scattering reaction rate
- Arrhenius parameters for reaction rates
- Resonance parameters
- Estimate dissociative electron attachment*
- Differential cross-sections
- Momentum transfer cross-sections
- Electron impact ionisation at all energies*
- Cross-sections for oriented molecules
- Rotational excitation cross-sections
- Vibrational excitation (non resonant)*
- Effective Core potentials for ionisation
- Approximation of electron scattering from condensed state: turning off long range moments in the outer region of the calculation

* features not present in standard R-matrix codes

What range of problems can be tackled with Quantemol-EC?

- Closed shell molecules
- Open shell molecules, radicals
- Neutral and positively charged species
- Large molecules (up to 25 atoms, preferably lighter than Ar)



Computer Physics
Communications
Volume 249, April 2020, 107092



CPC 50th anniversary article

UKRmol+: A suite for modelling electronic processes in molecules interacting with electrons, positrons and photons using the R-matrix method ☆

Zdeněk Mašín^a, Jakub Benda^b, Jimena D. Gorfinkiel^b, Alex G. Harvey^c, Jonathan Tennyson^d

Show more ▾

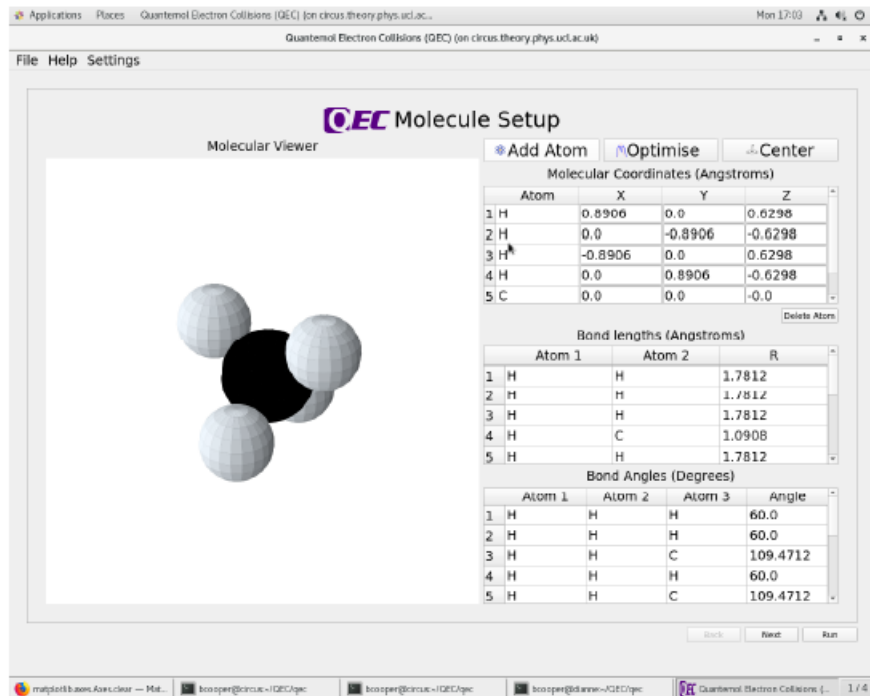
+ Add to Mendeley ◀ Share ▶ Cite

<https://doi.org/10.1016/j.cpc.2019.107092>

[Get rights and content](#)



QEC (続き)



- ※ Molpro とセットで利用
- ※ Ubuntu 等, Linux 環境が必要

Figure 1. Screenshot of the molecular set-up page in the Quantemol Electron Collision (QEC) graphical user interface (GUI) showing methane as an example. The screenshot was taken after the geometry had been optimized using Molpro and the coordinates automatically shifted to the center of mass.

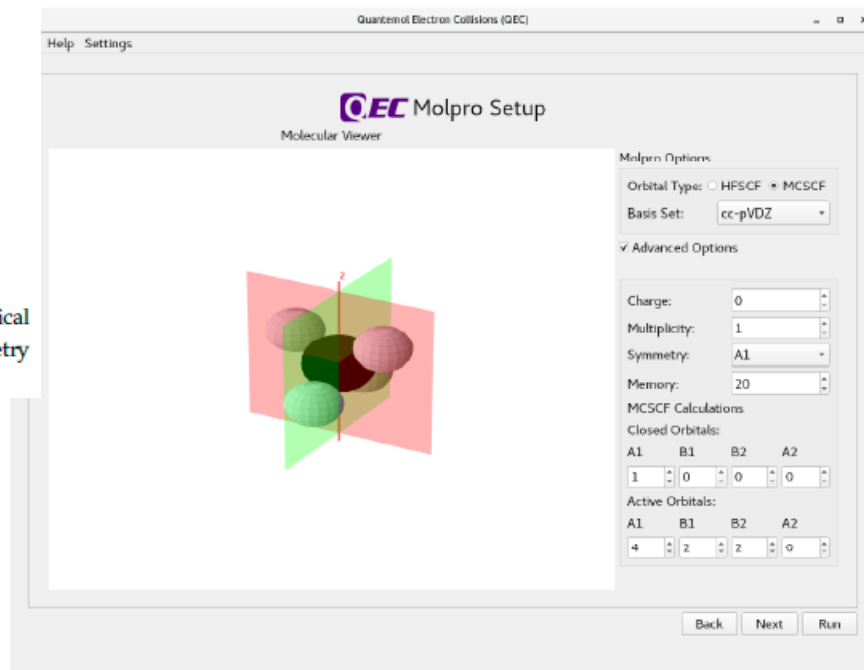
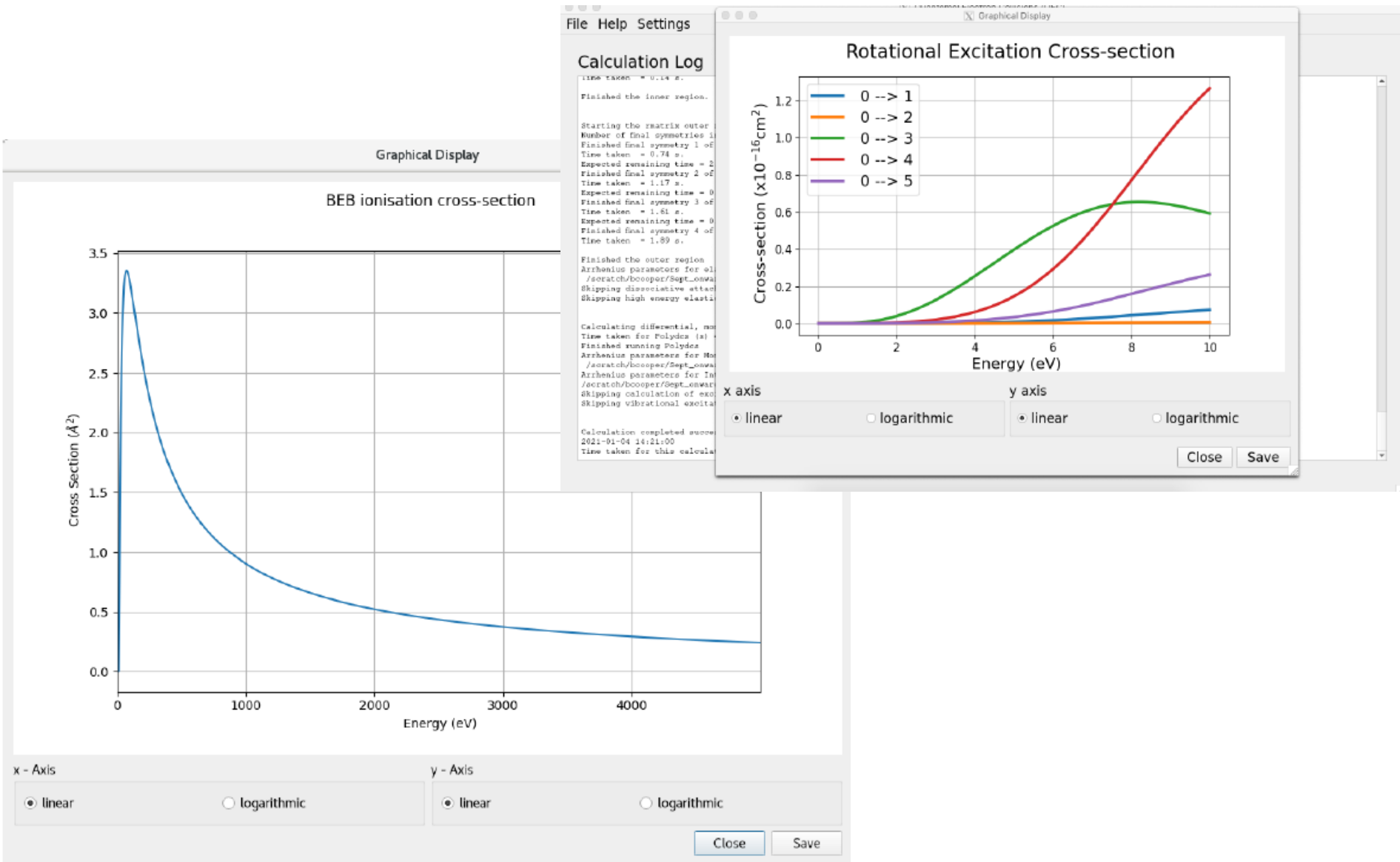


Figure 2. Screenshot of the page in the QEC GUI which sets up the molecular target calculation which is performed using Molpro.

QEC (続き) : ※ 計算結果の一例





過去の発表・論文



論文・技術レポート

Ion Energy Distributions at the Electron Cyclotron Resonance Position in
Electron Cyclotron Resonance Plasma

Seiji Samukawa, Yukito Nakagawa, Kei Ikeda, Jpn. J. Appl. Phys. 29 (1990) L2319-2321

NEC

Ion Current Density and Ion Energy Distributions at the Electron Cyclotron
Resonance Position in the **Electron Cyclotron Resonance Plasma**

Seiji Samukawa, Yukito Nakagawa, Kei Ikeda, Jpn. J. Appl. Phys. Pt. 1, 30, 2 (1991) 423-427

NEC

Numerical analysis of the pressure dependence of the etch rate in an **Al etching
reactor equipped with a helicon source**

Kei Ikeda, Yoshio Oshita, J. Vac. Sci. Technol. B16, 1, (1998) pp. 159-163

NEC

Three Dimensional Simulation for **Inductively Coupled Plasma Reactor
Employing Multi-Spiral Coil**

Kei IKEDA , Tomohiro OKUMURA, Vladimir KOLOBOV, J. Vac. Soc. Jpn. 50 (2007) 424

Panasonic

Generation and Transportation Mechanisms of Chemically Active Species by
Dielectric Barrier Discharge in a Tube for Catheter Sterilization

Takehiko Sato, Osamu Furuya, Kei Ikeda and Tatsuyuki Nakatani, Plasma Processes and Polymers, 5 (2008) pp. 606-614

Tohoku Univ.

Analysis of Process Plasma via Computer Simulations and Plasma Diagnostics,
for **N₂ Plasma and H₂ Plasma**

Modeling & Simulation Working Group, Semiconductor Equipment Association of Japan,
J. Vac. Soc. Jpn. 51, 12, 2008, pp. 807-813

SEAJ



論文・技術レポート (続き)

Target Erosion Simulation in Magnetron Sputtering and **Etch Rate Simulation in AI Etching** for Industrial Equipment

Kobayashi Tsukasa, Ikeda Kei, Reports of the Institute of Fluid Science, Tohoku University, Vol.10 (1998) pp. 67-76

Dependence of Deposition Characteristics by **Copper Chemical Vapor Deposition** on Gas Flow Shape

Akiko Kobayashi, Atsushi Sekiguchi, Kei Ikeda, Osamu Okada, Tomoaki Koide, Electronics and Communications in Japan 83 , 6 (Part II: Electronics), pp 1 - 7

SiC HTCVD simulation modified by sublimation etching

DENSO

KITOU Yasuo, MAKINO Emi, IKEDA Kei, NAGAKUBO Masao, ONDA Shoichi, Materials Science Forum, 2006, vol. 527-29 (1), pp. 107-110

Dielectric Barrier Discharge in Tube for Catheter Sterilization and its Mechanism for Radical Generation and Transportation

Tohoku Univ.

Takehiko Sato, Osamu Furuya, Kei Ikeda and Tatsuyuki Nakatani, International Conference on Plasma Medicine (ICPM-1), (2007) pp. 48-50

AIエッチング装置のプロセスシミュレーション 反応阻害物多層被覆モデルへの拡張

NEC

池田 圭, 小林 司, 塚田 勉, 大下 祥雄, 細井 信基, 月刊Semiconductor World 1997.4 pp. 79-82

昇華エッチングを考慮した**SiCの高温CVD**シミュレーション

木藤 泰男, 牧野 英美, 池田 圭, 永久保 雅夫, 恩田正一, デンソーテクニカルビューVol.12 No.2 (2007年12月)

DENSO



Athenasys の論文・講演

高周波・赤外集光一体型加熱装置の熱解析

池田 圭, 西澤 伸一, PAM Users' Conference in Asia 2009 (PUCA'09) 講演論文集 p.405

AIST

Application examples for **CVD** and **Plasma** simulation using CFD-ACE+

Kei Ikeda, KW tech 2009 conference

気相中のパーティクル生成及び基板近傍の壁面で生じる副生成反応（寄生成長）を考慮した**CVD** プロセスシミュレーション

化学工学会 反応工学部会 CVD反応分科会主催のシンポジウム（2009年12月）

- CVD反応シミュレーション -

パーティクル生成・寄生成長を考慮した**窒化物半導体・SiC**成長シミュレーション

化学工学会 反応工学部会 CVD反応分科会主催の講習会（2011年）

- 初級講座 プロセス・装置基礎解説とシミュレーションの応用～

Application example for **plasma** simulation

2012 KWEnC User Meeting at Oak Valley

TEL

誘導結合型プラズマ（**ICP**）の非定常解析

PUCA 2012 - ESI Users' Forum Japan

誘電体を考慮した容量結合型**プラズマ**のシミュレーション

PUCA 2013 - ESI Users' Forum Japan



Athenasys の論文・講演(続き)

plasma simulation using CFD-ACE+ Suite

Kei Ikeda, ICRP-8/SPP-31 Tutorial-3 : Medeling and Simulation

静磁場を考慮した**プラズマ**シミュレーション

池田 圭, 平成26年電気学会全国大会 (2014年3月) - 放電基礎パラメータと放電応用技術の最前線 II

静磁場を考慮した**プラズマ**シミュレーション

池田 圭, 2014年度 放電学会シンポジウム

静磁場を考慮した**プラズマ**シミュレーション

池田 圭, JIEED Japan Vol.57 No.3 (2014) p.27

CFD-ACE+ による**燃焼**の計算例

PUCA 2014 - ESI Users' Forum Japan

2D-Combined ICP/CCP numerical modeling for RF **plasma** source

M. Miyashita, K. Ikeda, and S. Ochi, Gaseous Electric Conference, KW3.00005, 2015

SHI

低温**プラズマ**シミュレーションの基礎

池田・中館・松永, J. Plasma Fusion Res. Vol.93, No.6 (2017) 287-291

流体モデルによるプロセス**プラズマ**シミュレーション (講座の一部)

池田 圭, J. Plasma Fusion Res. Vol.93, No.7 (2017) 327-331

Numerical simulation of **O2 premixed He plasma jets** interacting with a grounded target

T. Kobayashi and K. Ikeda, DPS 2018 - 40th International Symposium on Dry Process



Athenasys の論文・講演(続き)

Modeling study on **AC atmospheric pressure He plasma jets** interacting with a dielectric target

T. Kobayashi and K. Ikeda, DPS 2019 - 41th International Symposium on Dry Process

A computational model for **plasma enhanced chemical vapor deposition of silicon nitride**

K. Ikeda, DPS 2019 - 41th International Symposium on Dry Process

メタン高周波プラズマのモデリング

池田 圭, 第69回応用物理学会春季学術講演会 (2022年3月)

An Improved Calculation Scheme of Electron Flow in **Propagator Method for Solving the Boltzmann Equation**

T. Kobayashi and K. Ikeda, 75th Annual Gaseous Electronics Conference (2022年10月)

Importance of C_3H_y and $C_3H_y^+$ in **Modeling of Radio Frequency Methane Plasma**

K. Ikeda and T. Kobayashi, 75th Annual Gaseous Electronics Conference (2022年10月)

商用コードを用いた**プラズマシミュレーション**

池田 圭, 希薄プラズマ解析の産業応用に向けた数理モデルと数値計算手法の深化 (2023年11月, 九州大)



興味がありましたら、以下にお問合せ下さい。

inquire@athenasys.co.jp